

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently Amended) An opto-mechanical interface apparatus comprising:  
an optical hybrid;  
an electronic hybrid adapted to receive electronic components;  
an adapter fixture for fixing the electronic hybrid and the optical hybrid to one another to form a combined hybrid;  
a lower-capsule part; and  
an upper-capsule part adapted to mate with the lower-capsule part; ~~and~~-wherein mating of the upper-capsule part and the lower-capsule part encloses at least part of the combined hybrid.
2. (Original) The apparatus of claim 1, wherein the optical hybrid comprises:  
an optical chip;  
an optical-fiber connector; and  
a carrier.
3. (Original) The apparatus of claim 2, wherein the optical chip is selected from the group consisting of a transmitter chip and a receiver chip.
4. (Currently Amended) The apparatus of claim 1, wherein the lower-capsule part comprises an airing hole ~~airing holes~~.
5. (Currently Amended) The apparatus of claim 1, wherein the upper-capsule part comprises an airing hole ~~airing holes~~.

6. (Original) The apparatus of claim 1, wherein the upper-capsule part and the lower-capsule part are mated together via at least one of snap-locking, gluing, and ultra-sound welding.

7. (Original) The apparatus of claim 1, wherein:  
the upper-capsule part and the lower-capsule part are mated together; and  
the mated-together upper-capsule part and lower-capsule part form at least one cavity.

8. (Original) The apparatus of claim 7, wherein the at least one cavity comprises an upper cavity and a lower cavity.

9. (Original) The apparatus of claim 8, wherein:  
a first portion of the electronic components is contained within the upper cavity;  
and  
a second portion of the electronic components is contained within the lower cavity.

10. (Original) The apparatus of claim 9, wherein:  
the first portion of the electronic components comprises receiver electronics; and  
the second portion of the electronic components comprises transmitter electronics.

11. (Original) The apparatus of claim 1, wherein:  
the electronic hybrid comprises a printed circuit board (PCB); and  
the electronic components are mounted on the PCB.

12. (Currently Amended) The apparatus of claim 11 ~~[[1]]~~, wherein the PCB comprises:

- a pin for making an external electrical connection; and
- a stud for providing stability during assembly.

13. (Original) The apparatus of claim 1, wherein the lower-capsule part comprises a lead-through for receiving a protrusion of the electronic hybrid, the protrusion selected from the group consisting of a pin and a stud.

14. (Original) The apparatus of claim 1, wherein the lower-capsule part is adapted to permit accurate positioning of the combined hybrid.

15. (Original) The apparatus of claim 1, wherein the upper-capsule part is adapted to fix contents of the apparatus.

16. (Original) The apparatus of claim 1, wherein the optical hybrid comprises at least one of:  
at least one fiber;  
at least one transmitter; and  
at least one receiver.

17. (Currently Amended) A method of assembling an opto-mechanical interface apparatus, the method comprising:

forming a combined hybrid, the steps ~~step~~ of forming the combined hybrid comprising:

- attaching an adapter fixture to an electronic hybrid; and
- attaching an optical hybrid to the electronic hybrid;
- placing the combined hybrid in a first capsule part; and
- mating a second capsule part with the first capsule part, ~~and~~ wherein mating of the first capsule part and the second capsule part encloses at least part of the combined hybrid.

18. (Original) The method of claim 17, further comprising testing functionality of at least one component of the apparatus prior to the mating step.

19. (Original) The method of claim 17, wherein the steps are performed in the order listed.

20. (Original) The method of claim 17, wherein the step of mating is performed via at least one of gluing, snap-locking, and ultra-sound welding.

21. (Original) The method of claim 17, wherein the step of placing comprises positioning the combined hybrid in the first capsule part.

22. (Original) The method of claim 17, wherein the step of mating comprises fixing contents of the apparatus.

23. (Original) The method of claim 17, where in the first capsule part is a lower-capsule part and the second capsule part is an upper-capsule part.